

## N-CHANNEL SILICON POWER MOSFET

## FAP-IIA SERIES

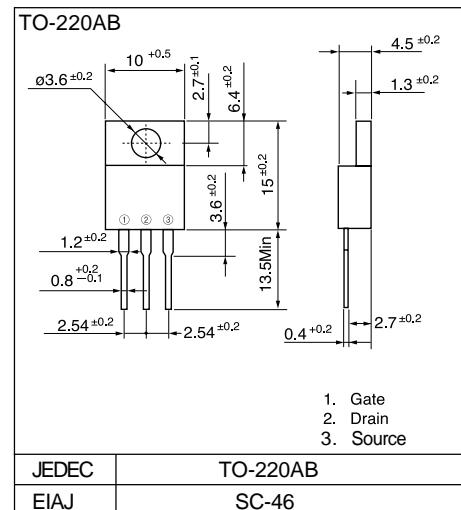
### ■ Features

- High speed switching
- Low on-resistance
- No secondary breakdown
- Low driving power
- High voltage
- $V_{GS} = \pm 30V$  Guarantee
- Avalanche-proof

### ■ Applications

- Switching regulators
- UPS
- DC-DC converters
- General purpose power amplifier

### ■ Outline Drawings

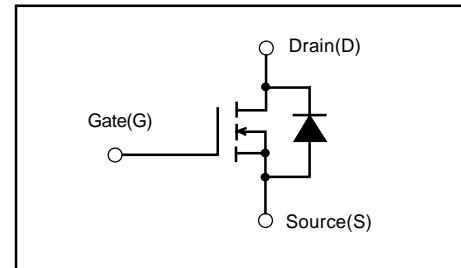


### ■ Maximum ratings and characteristics

#### ● Absolute maximum ratings ( $T_c=25^\circ\text{C}$ unless otherwise specified)

Item	Symbol	Rating	Unit
Drain-source voltage	$V_{DS}$	900	V
Continuous drain current	$I_D$	5	A
Pulsed drain current	$I_{D(\text{puls})}$	20	A
Continuous reverse drain current	$I_{DR}$	5	A
Gate-source peak voltage	$V_{GS}$	$\pm 30$	V
Max. power dissipation	$P_D$	80	W
Operating and storage temperature range	$T_{ch}$	+150	$^\circ\text{C}$
	$T_{stg}$	-55 to +150	$^\circ\text{C}$

### ■ Equivalent circuit schematic



#### ● Electrical characteristics ( $T_c = 25^\circ\text{C}$ unless otherwise specified)

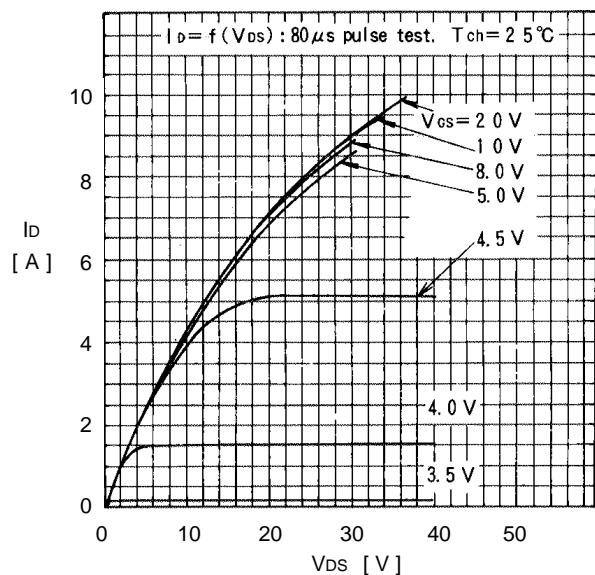
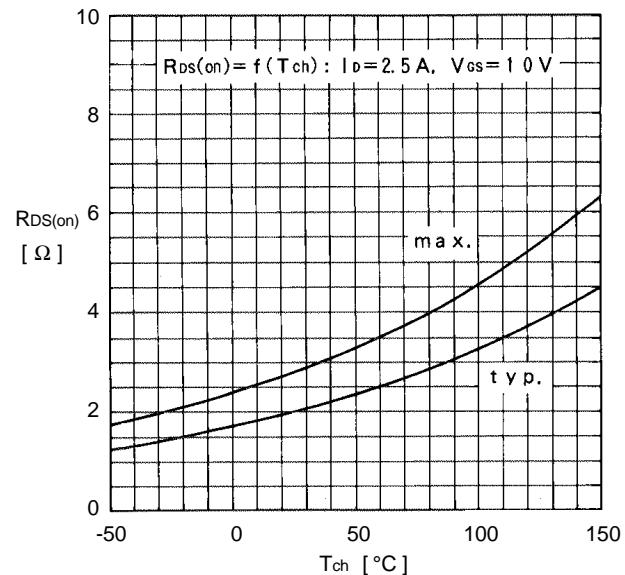
Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D=1\text{mA}$ $V_{GS}=0\text{V}$	900			V
Gate threshold voltage	$V_{GS(\text{th})}$	$I_D=1\text{mA}$ $V_{DS}=V_{GS}$	2.5	3.0	3.5	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=900\text{V}$ $V_{GS}=0\text{V}$		10	500	$\mu\text{A}$
				0.2	1.0	mA
Gate-source leakage current	$I_{GSS}$	$V_{GS}=\pm 30\text{V}$ $V_{DS}=0\text{V}$	10	100	100	nA
Drain-source on-state resistance	$R_{DS(\text{on})}$	$I_D=2.5\text{A}$ $V_{GS}=10\text{V}$	2.0	2.8	2.8	$\Omega$
Forward transconductance	$g_{fs}$	$I_D=2.5\text{A}$ $V_{DS}=25\text{V}$	3.0	6.0	6.0	S
Input capacitance	$C_{iss}$	$V_{DS}=25\text{V}$	1200	1800	1800	pF
Output capacitance	$C_{oss}$	$V_{GS}=0\text{V}$	120	180	180	
Reverse transfer capacitance	$C_{rss}$	$f=1\text{MHz}$	40	60	60	
Turn-on time $t_{on}$ ( $t_{on}=t_{d(on)}+t_r$ )	$t_{d(on)}$ $t_r$	$V_{CC}=600\text{V}$ $R_G=10\ \Omega$ $I_D=5\text{A}$	25	40	40	
Turn-off time $t_{off}$ ( $t_{off}=t_{d(off)}+t_f$ )	$t_{d(off)}$ $t_f$	$V_{GS}=10\text{V}$	25	40	130	ns
Avalanche capability	$I_{AV}$	$L=100\mu\text{H}$ $T_{ch}=25^\circ\text{C}$	85	130	70	
Diode forward on-voltage	$V_{SD}$	$I_F=2 \times I_{DR}$ $V_{GS}=0\text{V}$ $T_{ch}=25^\circ\text{C}$	5	0.93	1.4	V
Reverse recovery time	$t_{rr}$	$I_F=I_{DR}$ $V_{GS}=0\text{V}$ $di/dt=100\text{A}/\mu\text{s}$ $T_{ch}=25^\circ\text{C}$	400			ns

### ● Thermal characteristics

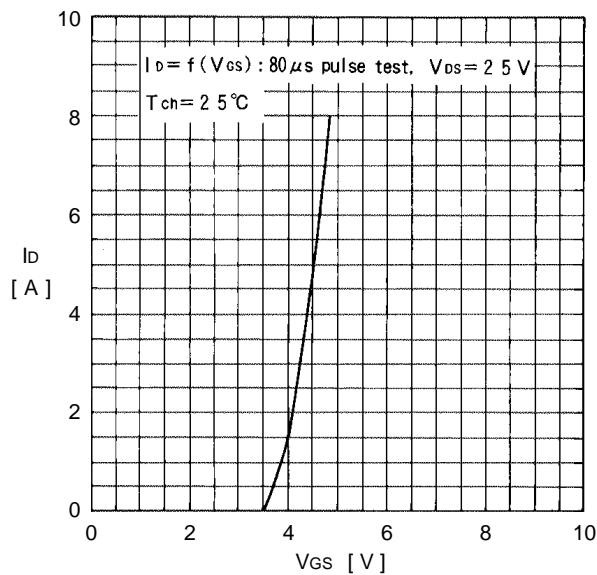
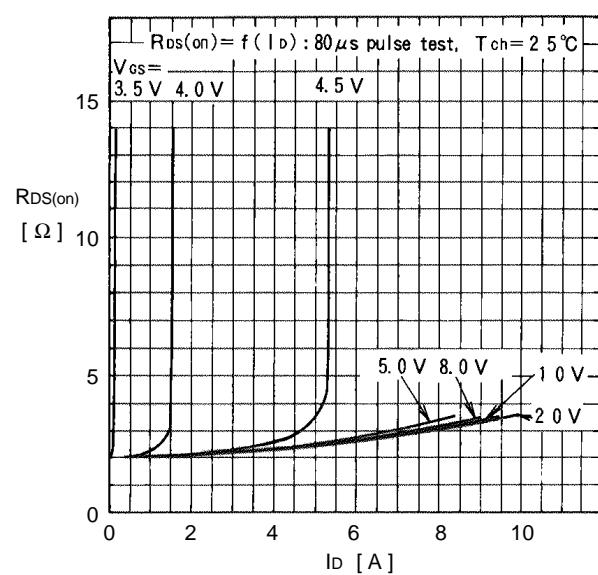
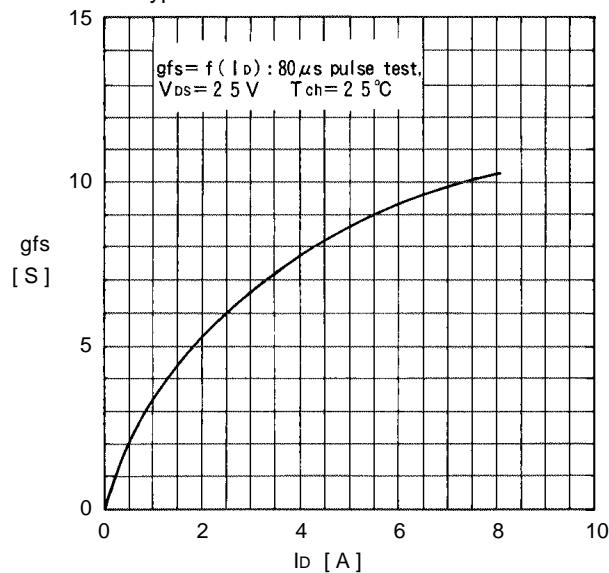
Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal resistance	$R_{th(ch-a)}$ $R_{th(ch-c)}$	channel to ambient channel to case			75.0 1.56	$^\circ\text{C/W}$ $^\circ\text{C/W}$

## ■ Characteristics

Typical output characteristics

On state resistance vs.  $T_{ch}$ 

Typical transfer characteristics

Typical Drain-Source on state resistance vs.  $I_D$ Typical forward transconductance vs.  $I_D$ Gate threshold voltage vs.  $T_{ch}$ 